LISTING OF CLAIMS:

1. (Withdrawn) A method for manufacturing a printed wiring board, the method comprising steps of:

forming an opening in a first resin film;

stacking the first resin film and a plurality of second resin films having no opening;

inserting an electric device, which has substantially the same size as the opening, in the opening; and

bonding the first and second resin films together by pressing and heating the first and second resin films after the step of inserting.

2. (Withdrawn) The method in claim 1, wherein a plurality of first resin films are stacked at the step of stacking in response to a thickness of the electric device if the thickness is greater than that of the first resin film.

3. (Withdrawn) The method in claim 2, wherein the total thickness of the first resin films is substantially equal to or smaller than the thickness of the electric device.

4. (Withdrawn) The method in claim 1, wherein an electrode is formed on a surface of the electric device, wherein the surface is parallel to the second resin films, wherein a conductive layer is formed on a surface of one of the second resin films, wherein a via, which includes a via-hole bottomed by the conductive layer and a material for electrical connection filled in the via-hole, is formed in the one of the second resin films at a position corresponding to the electrode,

and wherein the electrode and the conductive layer are electrically connected by the material for electrical connection in the step of bonding.

5. (Withdrawn) The method in claim 1, wherein a conductive layer is formed on a surface of one of the second resin films before the step of stacking and wherein the conductive layer and an electrode of the electric device are electrically connected before the step of inserting.

6. (Withdrawn) The method in claim 5, wherein the electrode is formed on a surface of the electric device, wherein the surface is parallel to the second resin films, wherein a via, which includes a via-hole bottomed by the conductive layer and a material for electrical connection filled in the via-hole, is formed in the one of the second resin films at a position corresponding to the electrode, and wherein the electrode and the conductive layer are electrically connected by the material for electrical connection.

7. (Withdrawn) The method in claim 5, wherein an electrode is formed on a surface of the electric device, wherein the surface is parallel to the second resin films, wherein the conductive layer is formed as a land at a position corresponding to the electrode, and wherein the electrode and the land are electrically connected.

8. (Withdrawn) The method in claim 5, wherein an electrode is formed on a surface of the electric device, wherein the surface is parallel to the second resin films, wherein the conductive

layer is formed as a land at a position corresponding to the electrode, and wherein the electrode and the land are electrically connected by wire bonding.

9. (Withdrawn) The method in claim 1, wherein the first and second resin films are made of thermoplastic resin.

10. (Withdrawn) The method in claim 9, wherein the first and second resin films are made of the same type of resin.

11. (Withdrawn) The method in claim 9, wherein the first and second resin films are heated at a temperature, at which the elastic modulus of the first and second resin films is 1-1000 MPa, in the step of bonding.

12. (Withdrawn) The method in claim 1, wherein the method includes a step of forming a heat releasing member on a surface of a stacked body of the first and second resin films after the step of inserting.

13. (Withdrawn) The method in claim 12, wherein the first and second resin films and the heat releasing member are bonded together by pressing and heating a stacked body of the first and second resin films and the heat releasing member after the step of forming the heat releasing member.

14. (Currently amended) A method for manufacturing a printed wiring board, the method comprising ~~steps of~~:

preparing a plurality of conductive layer films, each of which includes a resin film made of thermoplastic resin, a conductive layer formed on one side of the resin film, a bottomed via-hole which is bottomed by the conductive layer, and a conductive paste packed in the bottomed via-hole;

preparing a sheet member in which a recess or an opening is formed, the sheet member being made of the same thermoplastic resin to the resin film, wherein no conductive layer and no bottomed via-hole is formed in the sheet member;

~~forming a recess or an opening in a sheet member;~~

stacking ~~a plurality of resin~~ the plurality of conductive layer films; placing the sheet member on an outer surface of or in a stacked body of the ~~resin~~ conductive layer films, wherein the stacked body is formed at the step of stacking;

inserting an electric device in the recess or the opening formed in the sheet member; and

bonding the ~~resin~~ conductive layer films and the sheet member by pressing and heating the ~~resin~~ conductive layer films and the sheet member after the step of inserting.

15. (Currently amended) The method in claim 14, wherein the recess ~~and the~~ or the opening has substantially the same size as the electric device, which is to be inserted into the opening.

16. (Currently amended) The method in claim 15, wherein a depth of the recess ~~and the~~or the opening is substantially equal to or smaller than a thickness of the electric device, which is to be inserted into the opening.

17. (Currently amended) The method in claim 14,

wherein an electrode is formed on a surface of the electric device in a direction of stacking the conductive layer films and the sheet member, and

~~wherein the surface is parallel to the resin films, wherein a conductive layer is formed on a surface of one of the resin films, wherein a via, which includes a via hole bottomed by the conductive layer and a material for electrical connection filled in the via hole,~~

wherein the bottomed via hole is formed in ~~the one~~ one of the ~~resin~~ conductive layer films at a position corresponding to the ~~electrode~~electrodes, and wherein the electrode and the conductive layer are electrically connected by the ~~material for electrical connection~~ conductive paste in the step of bonding.

18. (Canceled)

19. (Canceled)

20. (Currently amended) The method in ~~claim 19~~claim 14, wherein the ~~resin~~ conductive layer films and the sheet member are heated at a temperature, at which the elastic modulus of the ~~resin~~ conductive layer films and the sheet member is 1-1000 MPa, in the step of bonding.

21. (Currently amended) The method in claim 14, wherein the method includes a step of forming a heat releasing member on an outer surface of ~~a stacked~~the stacked body of the ~~resin~~ conductive layer films and the sheet member after the step of inserting.

22. (Currently amended) The method in ~~claim 21~~claim 14, wherein the ~~resin~~ conductive layer films, the sheet member, and the heat releasing member are bonded together in the step of bonding.

23-30 (Canceled)